4V Drive Pch MOS FET

RSQ030P03

Structure

Silicon P-channel MOS FET

Features

- 1) Low On-resistance.(90mΩ at 4.5V)
- 2) High Power Package. (PD=1.25w)
- 3) High speed switching.
- 4) Low voltage drive. (4V)

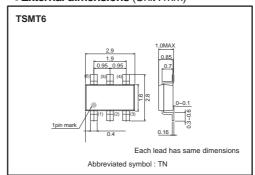
Applications

DC-DC converter

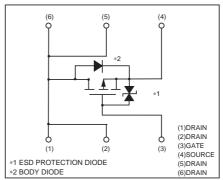
Packaging specifications

	Package	Taping
Туре	Code	TR
	Basic ordering unit (pieces)	3000
RSQ030P03	0	

●External dimensions (Unit : mm)



Equivalent circuit



● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		Voss	-30	V	
Gate-source voltage		Vgss	±20	V	
Drain current	Continuous	ΙD	±3	A	
	Pulsed	IDP *1	±12	А	
Source current (Body diode)	Continuous	Is	-1	А	
	Pulsed	Isp *1	-4	А	
Total power dissipation		P _D *2	1.25	W	
Channel temperature		Tch	150	°C	
Range of Storage temperature		Tstg	-55 to +150	°C	

^{*1} Pw≤10μs, Duty cycle≤1% *2 Mounted on a ceramic board

Thermal resistance Parameter Symbol Limits Unit Channel to ambient Rth(ch-a) * 100 °C / W



^{*} Mounted on a ceramic board.

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Gate-source leakage	Igss	-	-	±10	μΑ	Vgs=±20V, Vps=0V	
Drain-source breakdown voltage	V(BR)DSS	-30	_	_	V	I _D =-1mA, V _G S=0V	
Zero gate voltage drain current	IDSS	_	_	-1	μΑ	VDS=-30V, VGS=0V	
Gate threshold voltage	VGS(th)	-1.0	-	-2.5	V	VDS=-10V, ID=-1mA	
Static drain-source on-state resistance	RDS(on)*	_	60	80	mΩ	In=-3A, Vgs=-10V	
		-	90	125	mΩ	ID=-3A, VGS=-4.5V	
		_	100	140	mΩ	In=-1.5A, Vgs=-4.0V	
Foward transfer admittance	Y _{fs} *	1.5	-	-	S	VDS=-10V, ID=-1.5A	
Input capacitance	Ciss	-	440	-	pF		
Output capacitance	Coss	_	110	_	pF	V _{DS} =-10V,V _{GS} =0V f=1MHz	
Reverse transfer capacitance	Crss	-	80	_	pF		
Turn-on delay time	td(on) *	-	10	-	ns	ID=-1.5A VDD=-15V VGS=-10V RI=10Ω	
Rise time	tr *	-	13	_	ns		
Turn-off delay time	td(off) *	-	40	_	ns		
Fall time	t _f *	-	12	-	ns	$R_G = 10\Omega$	
Total gate charge	Qg	-	6.0	-	nC	V . 45V	
Gate-source charge	Qgs	-	1.6	_	nC	VDD = -15V VGS=-5V ID=-3A	
Gate-drain charge	Qgd	-	2.0	-	nC		

^{*}PULSED

●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	Vsp	-	-	-1.2	V	Is=-1A, VGS=0V

Electrical characteristic curves -Source On–State Resistance Ros(on)[mΩ] Static Drain–Source On–State Resistance Res(on)[mΩ] Drain Current: -lp (A) 0. Static Drain-0.0 0.001 $Drain\ Current: -I_D[A]$ Drain Current : -Ip[A] Gate-Source Voltage : -Vcs[V] Fig.2 Static Drain-Source On-State Fig.3 Static Drain–Source On–State Resistance vs.Drain Current Fig.1 Typical Transfer Characteristics Resistance vs. Drain Current Static Drain–Source On–State Resistance Resistance Resion[mΩ] Static Drain–Source On–State Resistance Res(on)[m Ω] Reverse Drain Current: -IpR[A] 0.01 Source-Drain Voltage: -Vsp[V] Drain Current : -Ip[A] $Drain\ Current: -I_D[A]$ Fig.6 Reverse Drain Current Source-Drain Current Fig.5 Static Drain-Source On-State Fig.4 Static Drain-Source On-State Resistance vs.Drain-Current Resistance vs.Drain-Current 10000 1000 Gate-Source Voltage: -Vcs [V] Switching Time : t [ns] Capacitance : C [pF] 1000 100 1 L Drain-Source Voltage : -Vps[V] Drain Current : -Ip[A] Total Gate Charge : Qg[nC] Fig.7 Typical Capactitance vs.Drain–Source Voltage Fig.8 Switching Characteristics Fig.9 Dynamic Input Characteristics

Measurement circuits

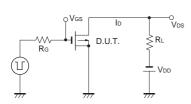


Fig.10 Switching Time Measurement Circuit

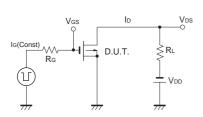


Fig.12 Gate Charge Measurement Circuit

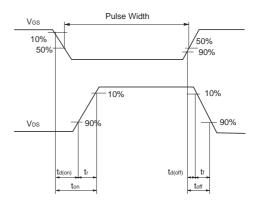


Fig.11 Switching Waveforms

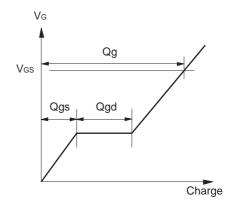


Fig.13 Gate Charge Waveforms

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